

Guidelines / Recommendations for “IPC 6010 Series”

(Application subject to customer – supplier agreement)



**Goal: Basic statement for using IPC-6010 series (e.g. IPC 6012-C),
practical implementation of the standards in line with requirements**

- Compliance with IPC-2221, the generic standard on PC design, is a precondition for meeting the requirements.
- PCB manufacturing is to meet the requirements of IPC-6011.
- Class 2 IPC-A-600 acceptance criteria apply as standard in PCB manufacturing. Qualified technologies and materials are to be used. Requirements of e.g. IPC-6012 and IPC 4101 are observed where feasible in terms of layout/design.
- Test coupons should reflect the structural integrity of the PCB technology.
- IPC-T-50 terms and definitions should be used to improve communication between parties.
- Process monitoring is a proven method of reducing the destructive testing of PCBs.
- Tests and inspections are to be performed in accordance with IPC-TM-650. The manufacturer is responsible for specifying test and inspection performance.
- Requirements to IPC class 3 must be agreed between customer and supplier.
- Copper wrap plating requirements at plugged vias are to be agreed according to individual layouts.
- Warp/twist requirements valid for symmetric stack up only but not for hybrid PCBs